

ABSTRACT

An integrated circuit has a wiring layer below an insulator layer. A pad comprises a conductive material that is on the insulator layer. The pad has a wirebond connection region and a probe pad region. An inspection mark is between the wirebond connection region and the probe pad region. The inspection mark comprises an opening in the insulator layer that is filled with the conductive material. In addition, a contact that is through the insulator layer is adapted to electrically connect the conductor wire in the wiring layer to the pad. The contact is formed of the same conductive material used for the pad and the inspection mark.